Electronic Patent Application Fee Transmittal						
Application Number:	10	10511883				
Filing Date:	19-Oct-2004					
Title of Invention:		Apparatus and method for depositing thin film on wafer using remote plasma				
First Named Inventor/Applicant Name:	Y	Young Hoon Park				
Filer:	Ja	James J. Merrick				
Attorney Docket Number:	YPL-0108					
Filed as Large Entity						
U.S. National Stage under 35 USC 371 Fil	ing	Fees				
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)	
Basic Filing:						
Pages:						
Claims:						
Miscellaneous-Filing:						
Petition:						
Patent-Appeals-and-Interference:						
Post-Allowance-and-Post-Issuance:						
Extension-of-Time:						
Extension - 3 months with \$0 paid		1253	1	1050	1050	

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			1050